IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Art Unit

: 1771

36th Floor

Examiner

: A. Singh : 09/101,251

1600 Market Street

Serial No. Filed

: July 15, 1998

Philadelphia, PA 19103

Inventors

Soichi İshibashi

Docket: 1066-98

Title

: Tetsuyuki Kyono

A MOLDING MATERIAL AND

A PRODUCTION PROCESS

THEREOF

Dated: July 11, 2000

DECLARATION OF AUSTIN R. MILLER

Assistant Commissioner for Patents Washington, DC 20231

Sir:

I, Austin R. Miller, declare that I have prepared the attached substitute specification entitled A MOLDING MATERIAL AND PRODUCTION PROCESS. This substitute specification is derived from the original Application Serial No. 09/101,251, filed July 15, 1998, and incorporates the amendments to the specification which are included in the prosecution. I hereby certify that to the best of my knowledge and belief, this substitute specification does not contain any new subject matter.

I also declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and thus such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: July 13, 2000

Austin R. Miller, Reg. No. 16,602

ب	Original Application				
	PCT National Application U.S. Designated Office				
	Continuation or Divisional Application				
	Continuation-in-Part Application				
	COMBINED DECLARATION, POWER OF ATTORNEY AND PETITION				
As a	below named inventor, I hereby declare that:				
Му	My residence, post office address and citizenship are as stated below next to my name,				
inve	I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled				
	which is described in the specification and claims				
	attached hereto.				
	☐ filed on				
	Application Serial No.				
	and was amended on				
	(if applicable)				
	which is described in International Application No. PCT/JP97/04049 filed November 6, 1997 and as amended on (if any),				
whice	ch I have reviewed and for which I solicit a United States patent.				
T 1	in his cases that I have received and understand the contents of the shows identified enceivation including the				

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I do not know and do not believe that this invention was ever known or used in the United States before my or our invention thereof or patented or described in any printed publication in any country before my or our invention thereof or more than one year prior to this application or said international application, or in public use or on sale in the United States of America more than one year prior to this application or said international application, or that the invention has been patented or made the subject of an inventor's certificate issued before the date of this application or said international application in any country foreign to the United States of America on an application filed by me or my legal representatives or assigns more than twelve months prior to this application or said international application, or that any application for patent or inventor's certificate on this invention has been filed in any country foreign to the United States of America prior to this application or said international application by me or my legal representatives or assigns except as identified below.

Attorney Docket No. 1066-98

Priority Claimed

Date of Filing (day, month, year)

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign applications for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Country

Number

293633/96	Japan		06,11,96	■ yes	□ no .
				□ yes	□ no
				☐ yes	□ no
				☐ yes	□ no
		,		☐ yes	□ no
application(s) listed be in the prior United States \$112, I acknowledge to	low and, insofar tes application(s) the duty to disclosed between the fil	as the subject matter in the manner proving se material inform	Code, §119 or §120 (as er of each of the claims of ided by the first paragrap ation as defined in Title for application(s) and the n	of this application of Title 35, U 37, Code of Fe	on is not disclos Inited States Coc ederal Regulation
(Application Serial No	.)	(Filing Date)		(Status) (patented,	pending,abandone
(Application Serial No	. 1	(Filing Date)	<u> </u>	(Status) (natanted	pending,abandon
	•/	(Filing Dute)		(Sicurs) (paternea,	penung,wanaon
POWER OF ATTORN	IEY: As a named	inventor, I hereby	appoint the following attorademark Office connected: Reg. No. 16,602 enbury Reg. No. 31,750 Reg. No. 38,412 Reg. No. P-43,0	orneys to prosected therewith: 2 0 2 1 2 1 2 1 2 1 2 1 2 1 3 4	-

I hereby petition for grant of a United States Letters Patent on this invention.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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	1. FULL NAME OF SOLE OR FIRST INVENTOR Soichi Ishibashi	INVENTOR'S SIGNATURE DATE 7/7/9	۶,				
H	RESIDENCE	CITIZENSHIP					
	Ehime Japan	Japanese					
Ħ	POST OFFICE ADDRESS						
	Seto-ryo, 1456, Oaza-Tsutsui, Masaki-cho, Iyo-gun, Ehime 791-31 Japan						
}	2. FULL NAME OF JOINT INVENTOR, IF ANY	INVENTOR'S SIGNATURE DATE					
3	Tetsuyuki Kyono	INVENTOR'S SIGNATURE DATE 7/2/98					
ā I	RESIDENCE	CITIZENSHIP					
0	Ehime Japan	Japanese					
n II	POST OFFICE ADDRESS	POST OFFICE ADDRESS					
5	11-12-901 Iwasaki-cho 2-chome, Matsuyama-shi, Ehime 790	Japan					
5	3. FULL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY	INVENTOR'S SIGNATURE DATE					
n	RESIDENCE	CITIZENSHIP					
	POST OFFICE ADDRESS						
4 0	4. FULL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY	INVENTOR'S SIGNATURE DATE					
	RESIDENCE	CITIZENSHIP					
	POST OFFICE ADDRESS						
	5. FULL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY	INVENTOR'S SIGNATURE DATE					
	RESIDENCE	CITIZENSHIP					
	POST OFFICE ADDRESS						
	6. FULL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY	INVENTOR'S SIGNATURE DATE					
	RESIDENCE	CITIZENSHIP .					
	POST OFFICE ADDRESS						
	7. FULL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY	INVENTOR'S SIGNATURE DATE					
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